



# SEMICONDUCTOR TECHNICAL DATA

## KMA4D5P20X

P-CH Trench MOSFET

### General Description

It's mainly suitable for battery pack or power management in cell phone, and PDA.

### FEATURES

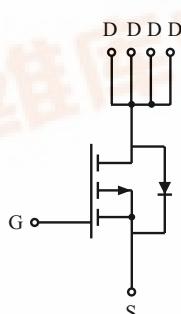
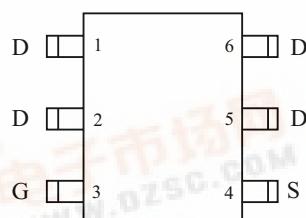
- $V_{DSS} = -20V$ ,  $I_D = -4.5A$ .
- Drain-Source ON Resistance.
  - :  $R_{DS(ON)} = 60m\Omega$  (Max.) @  $V_{GS} = -4.5V$ ,  $I_D = -4.5A$
  - :  $R_{DS(ON)} = 110m\Omega$  (Max.) @  $V_{GS} = -2.5V$ ,  $I_D = -3.3A$
- Super High Dense Cell Design for Extremely Low  $R_{DS(ON)}$

### MAXIMUM RATING ( $T_a = 25^\circ C$ )

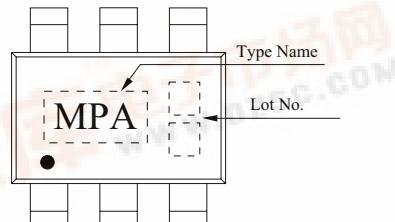
CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		$V_{DSS}$	-20	V
Gate-Source Voltage		$V_{GSS}$	$\pm 12$	V
Drain Current	DC	$I_D$ *	$\pm 4.5$	A
	Pulsed	$I_{DP}$ *	$\pm 16$	
Continuous Source Current		$I_S$	-1.3	A
Drain Power Dissipation	$T_a = 25^\circ C$	$P_D$ *	2.0	W
	$T_a = 70^\circ C$		1.3	
Maximum Junction Temperature		$T_j$	150	°C
Storage Temperature Range		$T_{stg}$	-55 ~ 150	°C
Thermal Resistance, Junction to Ambient		$R_{thJA}$ *	62.5	°C/W

\* : Surface Mounted on 1" × 1" FR4 Board,  $t \leq 5$  sec.

### PIN CONNECTION (TOP VIEW)



### Marking



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## ELECTRICAL CHARACTERISTICS (Ta=25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-20	-	-	V
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-20V	-	-	-1	μA
		V <sub>GS</sub> =0V, V <sub>DS</sub> =-16V, T <sub>j</sub> =70 °C (Note 3)	-	-	-5	
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.6	-	-1.3	V
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	-	-	±100	nA
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.5A (Note 2)	-	49	60	m Ω
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.3A (Note 2)	-	85	110	
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-4.5A (Note 2)	-	7	-	S
<b>Dynamic</b> (Note 3)						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-10V, R <sub>D</sub> =2.2 Ω V <sub>GS</sub> =-4.5V (Fig.1)	-	8.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.8	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	2.9	-	
Turn-on Delay time	t <sub>d(on)</sub>	V <sub>DS</sub> =-10V, R <sub>D</sub> =2.2 Ω V <sub>GS</sub> =-4.5V R <sub>G</sub> =6 Ω (Fig.2)	-	12	-	ns
Turn-on Rise time	t <sub>r</sub>		-	32	-	
Turn-off Delay time	t <sub>d(off)</sub>		-	64	-	
Turn-off Fall time	t <sub>f</sub>		-	40	-	
<b>Source-Drain Diode Ratings</b>						
Continuous Source Current	I <sub>S</sub>	V <sub>GS</sub> < V <sub>th</sub> (Note 1)	-	-	-1.3	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-4.5A, V <sub>GS</sub> =0V (Note 2)	-	-	-1.3	V

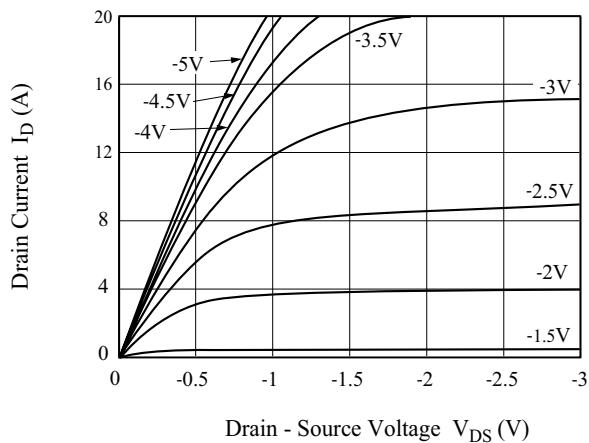
Note 1) Based on thermal dissipation from junction to ambient while mounted on a 1" × 1" FR4 Board.

Note 2) Pulse test : Pulse width ≤300μs, Duty Cycle ≤2%

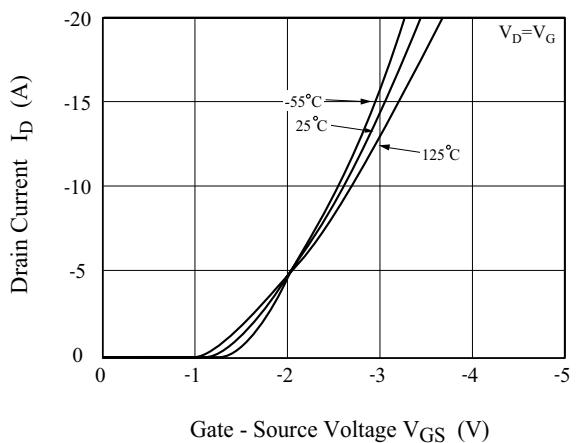
Note 3) Guaranteed by design, not subject to production testing.

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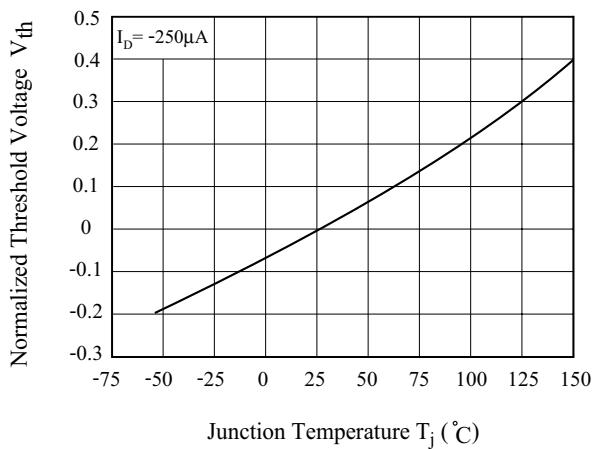
$I_D - V_{DS}$



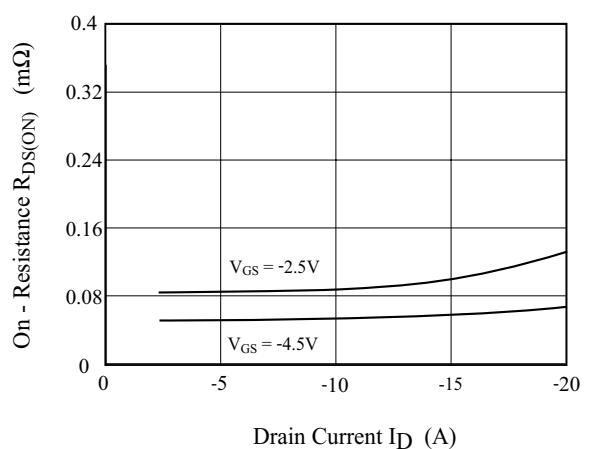
$I_D - V_{GS}$



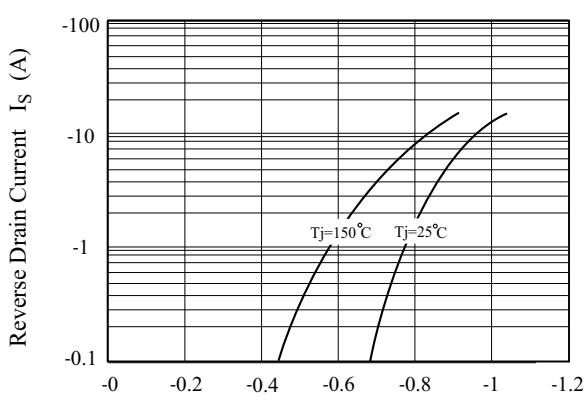
$V_{th} - T_j$



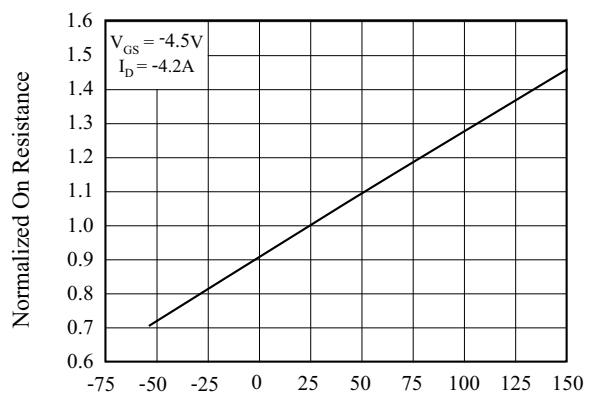
$R_{DS(ON)} - I_D$



$I_S - V_{SD}$



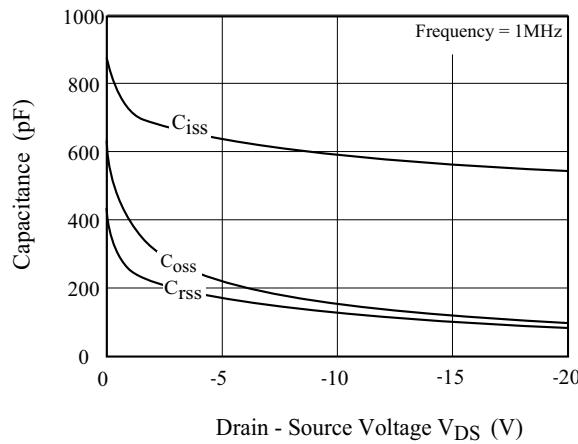
$R_{DS(ON)} - T_j$



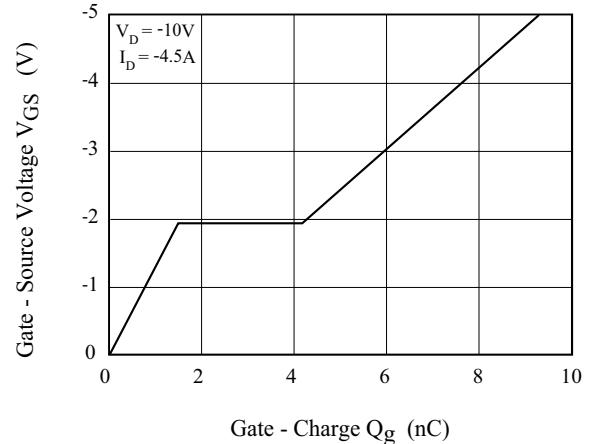
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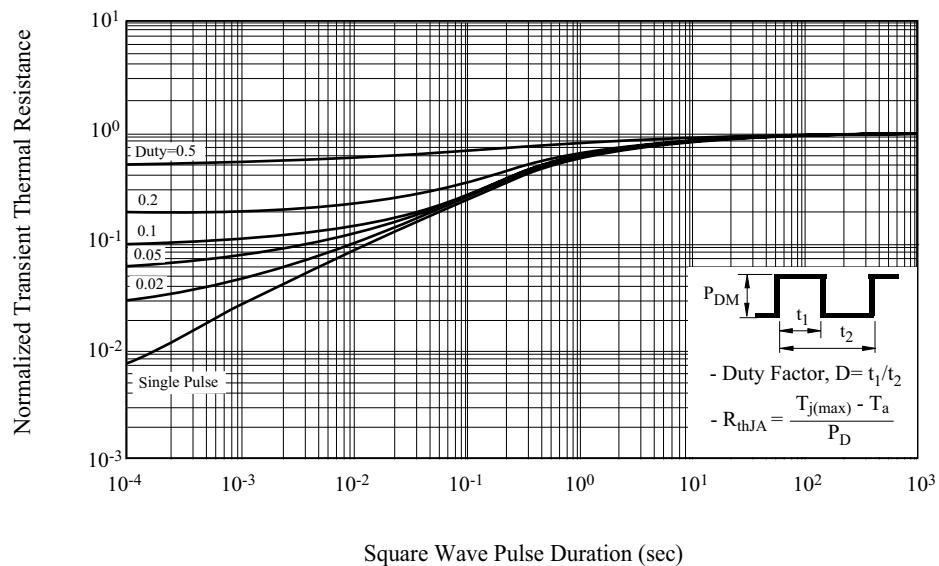
C - V<sub>DS</sub>



Q<sub>g</sub> - V<sub>GS</sub>



R<sub>th</sub>



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Fig. 1 Gate Charge

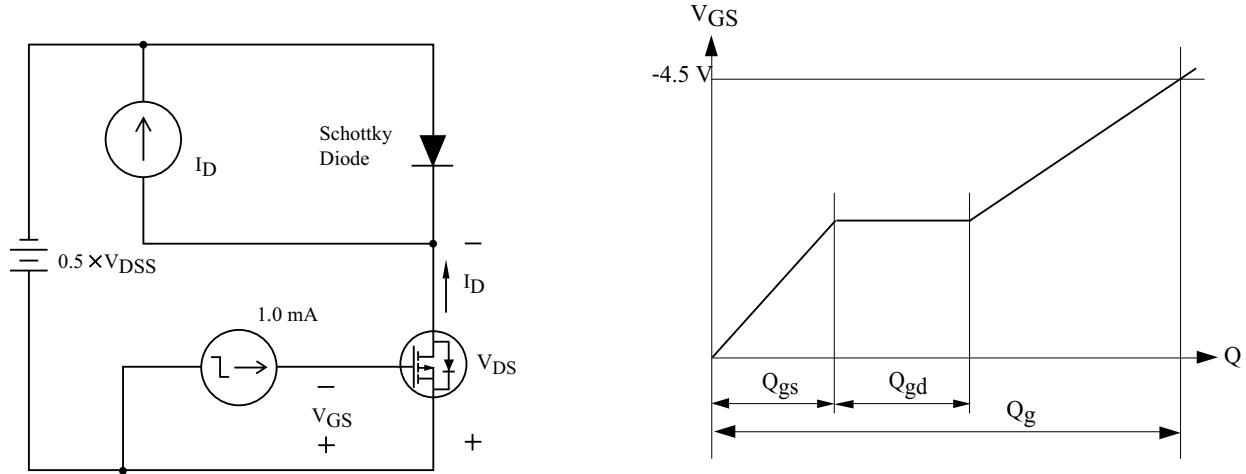


Fig. 2 Resistive Load Switching

